

Wi-Fi / System-on-Module Line Card

Laird Connectivity offers certified Wi-Fi modules that enable secure and reliable wireless connectivity, even in the harshest environments. Our modules are ideal for robust, business-critical connectivity in medical, industrial, and commercial settings where excellent RF performance, lower power consumption, simplified application development, and fast time to market are a must.



Enterprise Modules

Better with the Summit Suite Secure Connectivity Custom Firmware, Custom Suppliment, Connection Manager, And Much More.



Professional Modules



	60 Series	60 Series SOM	Summit SOM 8M Plus	Sterling-LWB5+	Sterling-LWB+	Sterling-EWB
Chipset	NXP 88W8997	Microchip ATSAMA5D36 NXP 88W8997	i.MX 8M Plus Processor NXP 88W8997	Infineon CYW4373E	Infineon CYW43439	Infineon CYW4343W + STM32F412 Cortex M4 MCU
802.11 Standards	802.11 a/b/g/n/ac (2.4 and 5 GHz)	802.11 a/b/g/n/ac (2.4 and 5 GHz)	802.11 a/b/g/n/ac (2.4 and 5 GHz)	802.11a/b/g/n/ac (2.4 and 5 GHz)	802.11a/b/g/n (2.4 GHz)	802.11 b/g/n
BT Standards	Dual-Mode Bluetooth v5.1	Dual-Mode Bluetooth v5.1	Bluetooth 5.3 - Dual Mode Classic (EDR) & BLE	Bluetooth 5.2 - Dual Mode Classic (EDR) & BLE	Bluetooth 5.2- Dual Mode Classic (EDR) & BLE	Bluetooth v5.1 BR/DR/LE
Type	SiP Package, M.2 2230-E Module with USB, SDIO, and PCIE variants	Complete Surface Mount System on Module	Complete Surface Mount System on Module	Surface Mount Module, M.2 2230 E-Key, USB Pluggable	SiP Package, Surface Mount Module	SiP Package or Surface Mount Module
Size (mm)	14 x 13 mm (SiP) 30 x 22 mm (PCB)	30 x 30 mm	40 x 47 mm	12 x 17 x 2.2 mm (SMT PCB) 22 x 30 x 3.1 mm (M.2 PCB) 17.5 x 47 x 11.7 mm (USB)	12 x 12 x 3 mm (SiP) 21 x 15 x 4 mm (PCB)	10 x 10 mm (SiP) 16 x 21 mm (PCB)
Tx Power (dBm)	Wi-Fi: 10 to 18 BT/BLE: 7 to 10	Wi-Fi: 10 to 18 BT/BLE: 7 to 10	+ 18 dBm (maximum)	+ 18 dBm (maximum)	+ 18 dBm (maximum)	Wi-Fi: 12.5 to 17.5 BT/BLE: 4 to 8.5
Rx Sensitivity (dBm)	Wi-Fi: -55 to -95 BT/BLE: -88 to -95	Wi-Fi: -55 to -95 BT/BLE: -88 to -95	Wi-Fi: -60 to -95 BLE: -88 to -98	Wi-Fi: -96 BT/BLE: -94	Wi-Fi: -89 to -94 BT/BLE: -83 to -91	Wi-Fi: -72 to -88 BT/BLE: -87 to -94
Temp. Range	-30°C to +85°C	-30°C to +85°C	-30°C to +85°C	-40°C to +85°C	-40°C to +85°C	-40° to +85° C
OS Support	Android, Linux	Onboard Linux OS	Onboard Linux OS and Zephyr RTOS	Linux	Android, Linux	On-board RTOS with WICED
Wi-Fi Security	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise, CNSA 192-bit	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise, CNSA 192-bit	WPA2-Personal, WPA2-Enterprise, WPA3-Personal	WPA2-Personal, WPA2-Enterprise, WPA3-Personal	WPA2-Personal
Certifications	FCC, IC, CE, MIC, AU/NZ, KCC, RCM	FCC, IC, CE, MIC, AU/NZ, KCC, RCM	FCC, IC, CE, MIC, RCM	FCC, IC, CE, MIC, RCM	FCC, IC, CE, MIC, RCM	FCC, IC, ETSI, MIC, RCM
Board Support Package	Kernel Backports, NetworkManager, Summit Suppliment and Yocto layer for Linux — broad kernel, BSP, and MPU compatibility.	Long Term Support Buildroot Linux with Summit Suite Vulnerability Monitoring & Remediation	Long Term Support Yocto Linux with Summit Suite Vulnerability Monitoring & Remediation	Kernel Backports, NetworkManager, and Yocto layer for Linux ensures broad kernel, BSP, and MPU compatibility.	Kernel Backports, NetworkManager, and Yocto layer for Linux ensures broad kernel, BSP, and MPU compatibility.	WICED SDK and New: AT Command Set!
	- Designed for Mission Critical applications 'Always-On Connectivity' through advanced software - Performance in harsh RF environments - Multi-OS (Android/Linux)		- Enterprise Security - Fast scanning & roaming - Industry-leading Support & Extended Warranty		- Designed for Fast Time-to-Market - Broad Certifications - Innovative Development Tools & Resources - Industry-leading Design Support	

Modules shown
are not actual size.